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P-Channel 15 V (D-S) MOSFET

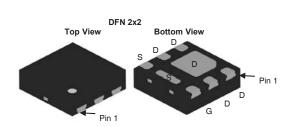
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(m\Omega)(Typ.)$	I _D (A) ^a	Q _g (Typ.)	
-15	13.5 at $V_{GS} = -4.5 \text{ V}$	- 17	16 nC	
-10	19.6 at V _{GS} = - 2.5 V		16 110	

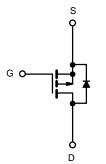
FEATURES

- DT-Trench Power MOSFET
- $\bullet\,$ 100 % R_g and UIS Tested
- Low Gate Charge
- High Power and current handing capability

APPLICATIONS

- PWM Application
- · Load Switch
- · Power management





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V _{DS}	-15	V		
Gate-Source Voltage	V _{GS}	±8	V		
Continuous Drain Current (T _{.I} = 150° C) ^a	T _A = 25 °C	I _D	- 17	A	
Continuous Diam Current (1) = 130 C)	T _A = 100 °C	ıD	- 11		
Pulsed Drain Current ^b	I _{DM}	- 68			
Maximum Power Dissipation ^c	T _C = 25 °C	P _D	5.5	· W	
Waxiiiuiii Fowei Dissipation-	T _C = 100 °C	- FD	2.2		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 150	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-Case (PCB Mount) ^d	R _{thJA}	22.7	°C/W	

Notes

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of R_{0JA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper,in a still air environment with Ta=25 °C.



PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V _{DS}	V_{DS} $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	-0.4	-	-1	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current		V _{DS} = -12 V, V _{GS} = 0 V	-	-	-1	μA
	I _{DSS}	V _{DS} =-12V, V _{GS} = 0 V, T _J = 125 °C	-	-	-100	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -5 \text{ V}, V_{GS} = -5 \text{ V}$	-10	-	=	Α
Drain-Source On-State Resistance ^a	D ·	V _{GS} = -4.5 V, I _D = - 5 A	-	13.5	3.5 18	~ 0
	R _{DS(on)}	V _{GS} = -2.5 V, I _D = - 4 A	-	19.6	26	mΩ
Forward Transconductance ^a	g fs	V _{DS} = - 5 V, I _D = - 5 A	-	14	-	S
Dynamic ^b						
Input Capacitance	C _{iss}		-	1450	-	pF
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 10 V, f = 1 MHz	-	320	-	
Reverse Transfer Capacitance	C _{rss}		-	280	-	
Total Gate Charge ^c	Qg		-	16	-	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5 \text{ A}$	-	3.5	-	nC
Gate-Drain Charge ^c	Q_{gd}		-	4.2	-	
Turn-On Delay Time ^c	t _{d(on)}		-	16	-	
Rise Time ^c	t _r	$V_{DD} = -10 \text{ V}, R_g = 3 \Omega, R_L = 2 \Omega$	-	65	-	
Turn-Off Delay Time ^c	t _{d(off)}	Vgs = - 4.5 V	-	72	-	ns
Fall Time ^c	t _f]	-	63	-	
Drain-Source Body Diode Ratings and	Characterist	tics ^b (T _J = 25 °C)		•		
Continuous Source-Drain Diode Current	I _S	T _A = 25 °C	-	-	-11.5	Α
Pulsed Current	ulsed Current I _{SM}		-	-	-46	Α
Forward Voltage ^a V_{SD} $I_F = -5 \text{ A}, V_{GS} = 0 \text{ V}$		_	_	-1.2	V	

Notes

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those in dicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended pe riods may affect device reliability.



TYPICAL CHARAC TERISTICS (25 °C, unless otherwise noted)

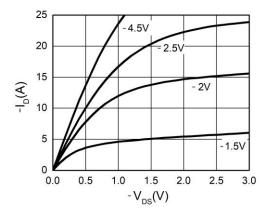


Figure 1. Output Characteristics

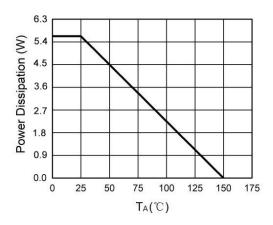


Figure 3. Power Dissipation

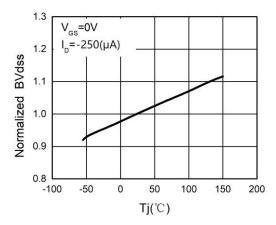


Figure 5. BV_{DSS} vs Junction Temperature

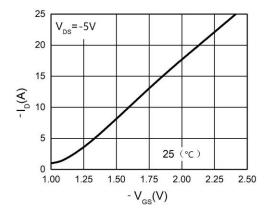


Figure 2. Transfer Characteristics

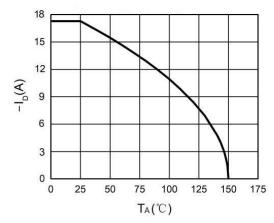


Figure 4. Drain Current

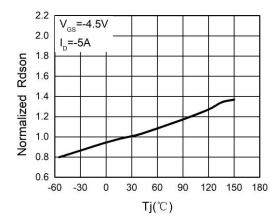


Figure 6. R_{DS(ON)} vs Junction Temperature



10²

10¹

10°

0.2 0.4

TYPICAL CHARAC TERISTICS (25 °C, unless otherwise noted)

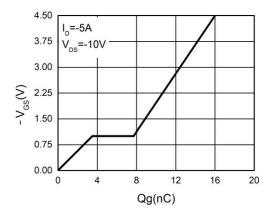
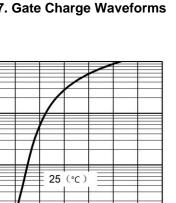


Figure 7. Gate Charge Waveforms



1.2 1.4

Figure 9. Body-Diode Characteristics

 $-V_{SD}(V)$

0.6 0.8 1.0

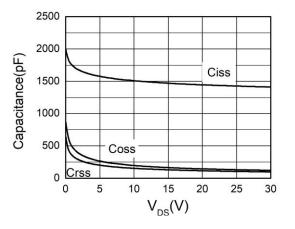


Figure 8. Capacitance

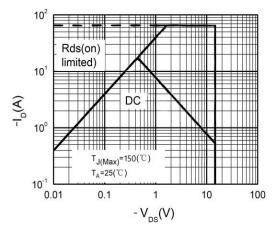
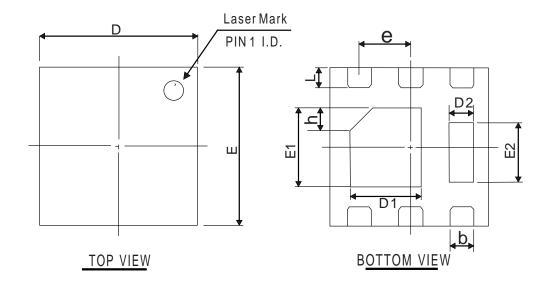
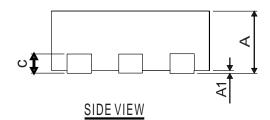


Figure 10. Maximum Safe Operating Area



DFN 2X2 PACKAGE OUTLINE





COMMON DIMENSIONS (UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
Α	0.60	0.75	0.90
A1	0.00	0.02	0.10
b	0.15	0.25	0.40
D	1.80	2.00	2.25
E	1.80	2.00	2.25
D1	0.70	0.90	1.10
E1	0.75	1.00	1.20
D2	0.15	0.30	0.45
E2	0.45	0.75	0.95
L	0.15	0.25	0.40
h	0.15	0.25	0.40
С	0.203 REF		
е	0.65 BSC		

Other thickness dimensions are as follows

Α	0.50	0.55	0.60
Α	0.40	0.45	0.50





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